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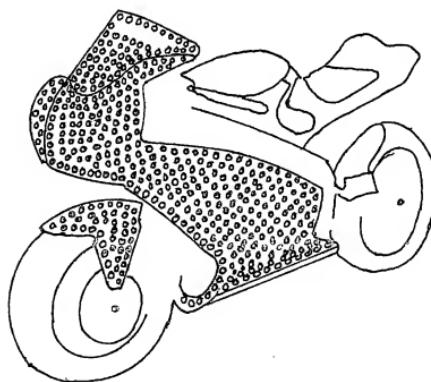
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(54) Title: METHOD FOR REDUCING KINETIC FRICTION



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(57) Abstract: This specification describes a method for reducing kinetic friction by means of profiled surface patterns when devices and appliances of different materials, sizes and shapes are in contact with air, gas and liquid masses. The method can be used above all to achieve savings in energy consumption in means of transport by providing their surfaces with profiled surface patterns. The method is also suited for use in numerous other applications where kinetic friction between the aforesaid masses and devices and appliances is to be reduced for a specific reason, but those are not covered by the scope of this application.